

CLAIMS

I claim:

1. A test probe comprising:

one or more contact devices that are designed to provide a contact point for establishing
an electrical contact between each contact device of the one or more contact devices and a
device-under-test,

wherein

each contact device includes a bonding wire that is bonded to a first point and a second
point on the test probe, and

the contact point of each contact device is located on the bonding wire that forms the
contact device, between the first point and the second point.

2. The test probe of claim 1, wherein

the first point and the second point on the test probe of each contact device are
substantially adjacent.

3. The test probe of claim 2, wherein

the test probe includes one or more bond pads, and

the first point and the second point of each contact device on the test probe are located on
a common bond pad of the one or more bond pads.

4. The test probe of claim 3, wherein

the test probe includes an integrated circuit substrate, and

the one or more contact devices are located on the integrated circuit substrate.

5. The test probe of claim 4, wherein

the test probe includes one or more test circuits that are operably coupled to the one or
more contact devices.

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12. An integrated circuit comprising:
a plurality of bond pads, and
one or more contact devices, wherein
each of the one or more contact devices includes a bonding wire that is bonded to a first
5 point and a second point on the plurality of bond pads.
13. The integrated circuit of claim 12, wherein
the first point and the second point of the bonding wire are located on a common bond
pad.
- 10 14. The integrated circuit of claim 12, wherein
the first point of the bonding wire is located adjacent the second point of the bonding
wire.
15. The integrated circuit of claim 12, wherein
the bonding wire is formed between the first point and the second point to produce a
vertex that facilitates electrical contact between the contact device and another integrated circuit.
16. The integrated circuit of claim 12, wherein
the bonding wire includes a resilient material.

17. A method of manufacturing an integrated circuit, including:

forming a plurality of bond pads on an integrated circuit substrate,
attaching at least one contact device on the integrated circuit substrate by bonding a
bonding wire to a first point and to a second point within the plurality of bond pads, the bonding
5 wire forming the at least one contact device.

18. The method of claim 17, wherein

the first point and the second point of the at least one contact device are located on a
common bond pad.

19. The method of claim 17, wherein

the first point of the at least one contact device is adjacent to the second point of the at
least one contact device.

20. The method of claim 17, wherein

the bonding wire is formed between the first point and the second point to produce a
vertex that is substantially above an upper-layer plane of the integrated circuit substrate.

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